

ON Semiconductor 9/20/2020

Base Part	NCP135	HF	Pb-free
Orderable Part	NCP135AMT040TBG	Total weight (mg)	10.02

Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.48	Silicon (Si)	7440-21-3	100
Die Attach	0.04	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3	0.5
		Isobornyl Methacrylate	7534-94-3	6
		Silver (Ag)	7440-22-4	81.5
		Isobornyl Acrylate	5888-33-5	6
		Tricyclo[5.2.1.0 ^{2,6}]decanedimethanol Diacrylate (C ₁₈ H ₂₄ O ₄)	42594-17-2	6
Lead Frame	4.16	Silver (Ag)	7440-22-4	1
		Tin (Sn)	7440-31-5	0.25
		Zinc (Zn)	7440-66-6	0.22
		Chromium (Cr)	7440-47-3	0.25
		Copper (Cu)	7440-50-8	98.28
Mold Compound-Black	5.09	Epoxy resins	129915-35-1	5
		Silica Amorphous (SiO ₂)	7631-86-9	5
		Carbon Black (C)	1333-86-4	0.4
		Aluminum Hydroxide (Al(OH) ₃)	21645-51-2	2.3
		Fused Silica (SiO ₂)	60676-86-0	85
		Phenolic Resin (Novolac)	9003-35-4	2.3
Plating	0.2	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.05	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>